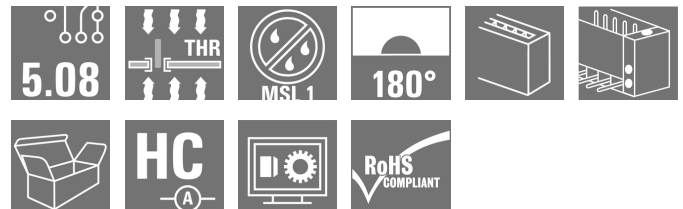


**OMNIMATE Signal - series BL/SL 5.08
SL-SMT 5.08HC/12/180F 3.2SN BK BX**

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Similar to illustration

High-temperature-resistant pin header, packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Type	SL-SMT 5.08HC/12/180F 3.2SN BK BX
Order No.	1820630000
Version	PCB plug-in connector, male header, Flange, THT/THR solder connection, 5.08 mm, Number of poles: 12, 180°, Solder pin length (l): 3.2 mm, tinned, Black, Box
GTIN (EAN)	4032248316595
Qty.	24 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

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Technical data

Dimensions and weights

Width	70.96 mm	Width (inches)	2.794 inch
Height	15.2 mm	Height (inches)	0.598 inch
Height of lowest version	12 mm	Depth	8.5 mm
Depth (inches)	0.335 inch	Net weight	6.12 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	180°
Number of poles	12	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm
Tolerance of solder pin position	± 0.15 mm	Solder pin dimensions	d = 1.2 mm, Octagonal
Solder eyelet hole diameter (D)	1.5 mm	Solder eyelet hole diameter tolerance (D)	+ 0.1 mm
L1 in mm	55.88 mm	L1 in inches	2.2 inch
Number of rows	1	Pin series quantity	1
Volume resistance	≤ 5mΩ	Can be coded	Yes
Plugging cycles	25	Plugging force/pole, max.	9 N
Pulling force/pole, max.	7 N		

Material data

Insulating material	LCP GF	Colour	Black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
GWIT	930 °C	GWFI	960 °C
Contact material	CuMg	Contact surface	tinned
Layer structure of solder connection	1-3 µm Ni / 2-4 µm Sn matt	Layer structure of plug contact	1-3 µm Ni / 2-4 µm Sn matt
Storage temperature, min.	-25 °C	Storage temperature, max.	55 °C
Max. relative humidity during storage	80 %	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

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Technical data
Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group D / CSA)	18.5 A	Reference to approval values	Specifications are maximum values, details - see approval certificate.

Rated data acc. to UL 1059

Institute (UR)		Certificate No. (UR)	E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	18.5 A	Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

Packaging	Box	VPE length	35 mm
VPE width	110 mm	VPE height	165 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02
eClass 10.0	27-44-04-02	UNSPSC	30-21-18-10

Notes

Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.		
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.		

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Technical data

Approvals

Approvals



ROHS

Conform

Downloads

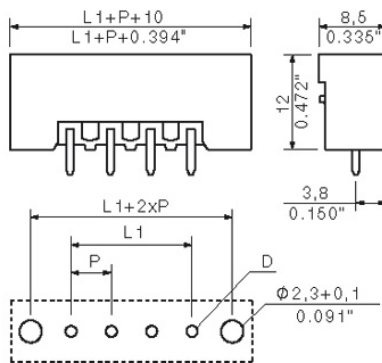
Approval/Certificate/Document of Conformity	CB Certificate CB Testreport Declaration of the Manufacturer
Brochure/Catalogue	FL DRIVES EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN CAT 2 PORTFOLIOGUIDE EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL INVERTER EN FL_BASE_STATION_EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN
Engineering Data	WSCAD
Engineering Data	STEP
White paper surface mount technology	Download Whitepaper

OMNIMATE Signal - series BL/SL 5.08 SL-SMT 5.08HC/12/180F 3.2SN BK BX

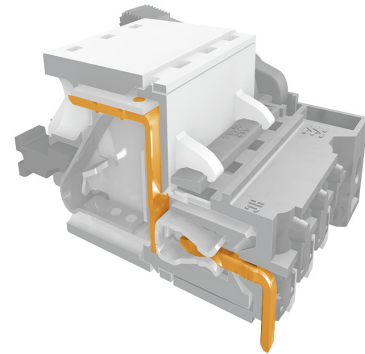
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Drawings

Dimensional drawing



Product benefits



Safe power transmission

Product benefits Proven properties

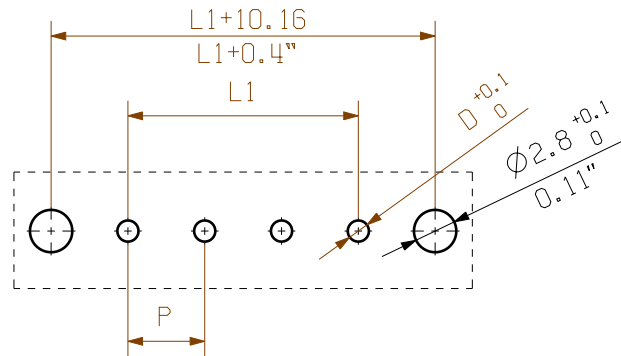
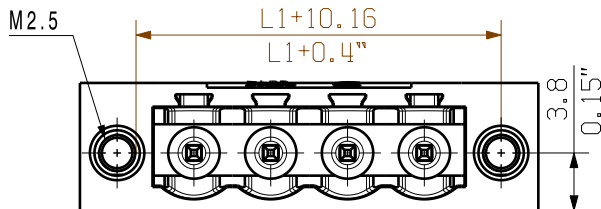
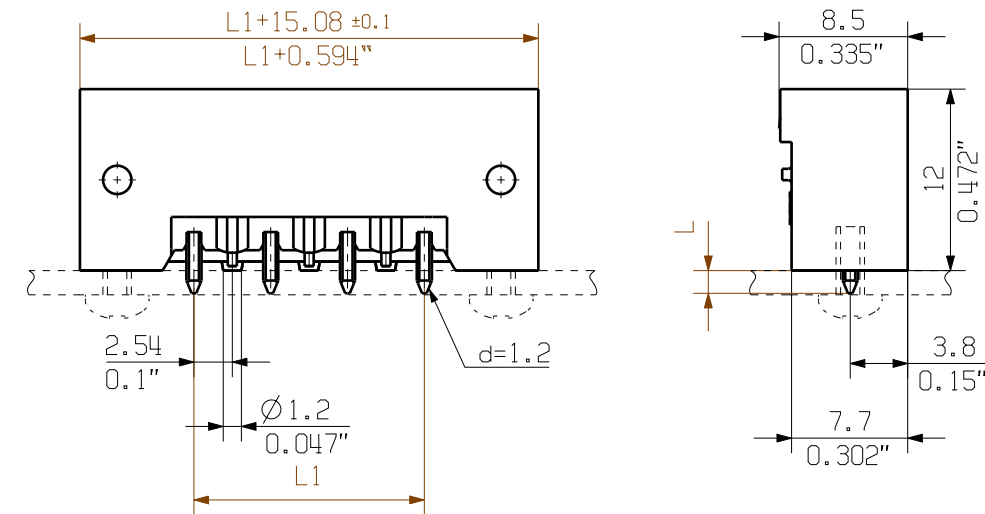


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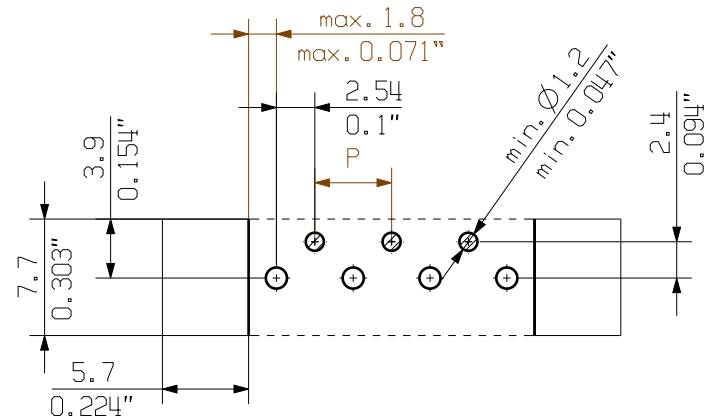
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Dimensions without tolerances are no check dimensions

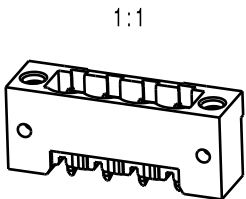
The English version is binding



HOLE PATTERN



PASTE-FREE AREA



1:1

D = 1.4/0.055" or 1.5/0.059" (REFLOW SOLDERING)
RECOMMENDATION FOR AUTOMATIC ASSEMBLY
(1.4mm FOR n=2...8 / 1.5mm for n=9...24)

n = POLZAH/ NO OF POLES

P = RASTER/PITCH

SHOWN: SL-SMT 5.08HC/04/180 F

1,5	0,0
	-0,3
3,2	0,1
	-0,3
4,5	0,1
	-0,3
STIFTLAENGE L	TOLERANZ

24	116,84	4,600
23	111,76	4,400
22	106,68	4,200
21	101,60	4,000
20	96,52	3,800
19	91,44	3,600
18	86,36	3,400
17	81,28	3,200
16	76,20	3,000
15	71,12	2,800
14	66,04	2,600
13	60,96	2,400
12	55,88	2,200
11	50,80	2,000
10	45,72	1,800
9	40,64	1,600
8	35,56	1,400
7	30,48	1,200
6	25,40	1,000
5	20,32	0,800
4	15,24	0,600
3	10,16	0,400
2	5,08	0,200
n	L1 [mm]	L1 [Inch]

For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components alone.
The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.
The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.
Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

DIN ISO 2768-m		106339/4 30.07.18 HERTEL_S		00	Cat.no.: .	
Modification		Date		Name	C 34148	
Drawn		30.11.2007		HELIS_MA	Issue no. 23	
Responsible		01.08.2018		KOCH_JG	Sheet 04 of 04 sheets	
Checked		01.08.2018		KOCH_JG	Product file: SL-SMT 5.08HC	
Approved		01.08.2018		LANG_T	7280	

Weidmüller

SL-SMT 5.08HC/.../180...
STIFTELEISTE
MALE HEADER

Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

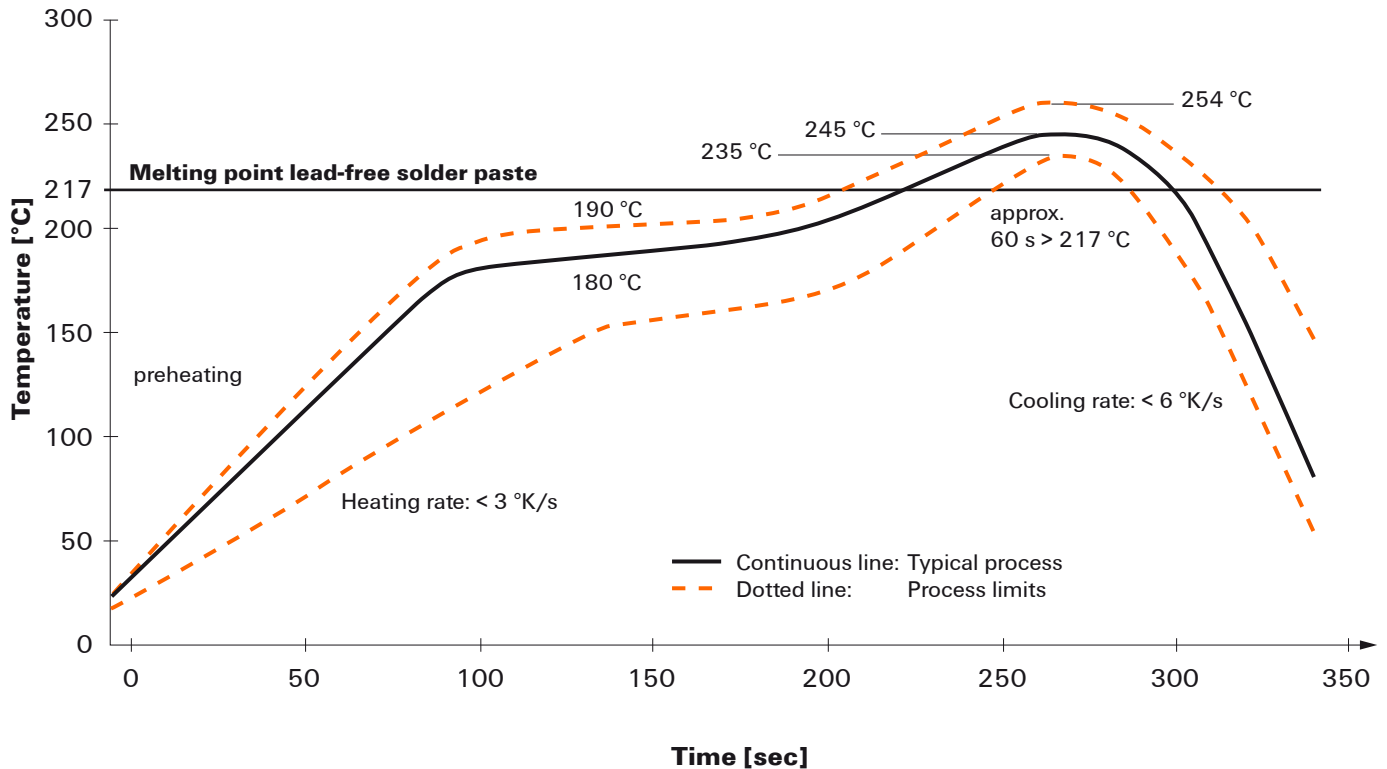
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.